

CLAIMS

What is claimed is:

1. A method for fabricating optical elements, comprising:
forming topographic features on a surface of an optical element substrate;
5 mechanically polishing the surface of the substrate to modify the features; and
dicing the substrate into the optical elements.
2. A method as claimed in claim 1, wherein the step of forming the topographic features comprises forming blind holes into the substrate
3. A method as claimed in claim 1, wherein the step of forming the topographic features comprises forming blind holes, having mesa profiles, into the substrate.
4. A method as claimed in claim 1, wherein the step of forming the topographic features comprises forming a feature projecting from the substrate.
5. A method as claimed in claim 1, wherein the step of forming the topographic features comprises forming mesas in the substrate.
6. A method as claimed in claim 1, wherein the step of forming the topographic features comprises etching a blind hole into the substrate to a depth of a material layer.
7. A method as claimed in claim 1, wherein the step of forming the topographic features comprises etching blind holes into the substrate in a timed process.
8. A method as claimed in claim 1, wherein the step of polishing the surface comprises performing chemical mechanical polishing of the surface.
9. A method as claimed in claim 1, further comprising optically coating the surface after the polishing step.
10. A method as claimed in claim 9, wherein the step of optically coating the surface comprises depositing a highly reflective layer on the surface.

11. A method as claimed in claim 9, wherein the step of optically coating the surface comprises depositing an antireflective layer on the surface.

12. A method as claimed in claim 1, further comprising optically coating the surface after the polishing step and before the dicing step.

5 13. A method as claimed in claim 1, wherein the step of dicing the substrate comprises sawing the substrate.

14. A method as claimed in claim 1, wherein the step of dicing the substrate comprises cleaving the substrate.